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October 2012

# FAN73833 Half-Bridge Gate-Drive IC

#### **Features**

- Floating Channel for Bootstrap Operation to +600V
- Typically 350 mA / 650 mA Sourcing/Sinking Current Driving Capability for Both Channels
- Extended Allowable Negative V<sub>S</sub> Swing to -9.8 V for Signal Propagation at V<sub>DD</sub>=V<sub>BS</sub>=15 V
- 3.3 V and 5 V Input Logic Compatible
- Outputs in Phase with Input Signals
- Built-in UVLO Functions for Both Channels
- Built-on Shoot-Through Prevention Circuit
- Built-in Common-Mode dv/dt Noise Canceling Circuit
- Internal Dead-Time Typically 400 ns

### **Applications**

- SMPS
- Motor Drive Inverter
- Fluorescent Lamp Ballast
- HID Ballast

### Description

The FAN73833 is a half-bridge gate-drive IC for driving MOSFETs and IGBTs, operating up to +600 V.

Fairchild's high-voltage process and common-mode noise canceling technique provide stable operation of high-side driver under high dv/dt noise circumstances.

An advanced level-shift circuit allows high-side gate driver operation up to  $V_{S}$ =-9.8 V (typical) for  $V_{BS}$ =15 V.

The UVLO circuits for both channels prevent malfunction when  $V_{DD}$  and  $V_{BS}$  are lower than the specified threshold voltage.

Output drivers typically source/sink 350 mA / 650 mA, respectively, which is suitable for all kinds of half- and full-bridge inverters.

8-SOP



### **Ordering Information**

Part Number	Package	Operating Temperature Range	Packing Method	
FAN73833M	8-SOP	-40°C to +125°C	Tube	
FAN73833MX	0-30P	-40 C to +125 C	Tape & Reel	

### **Typical Application Circuit**

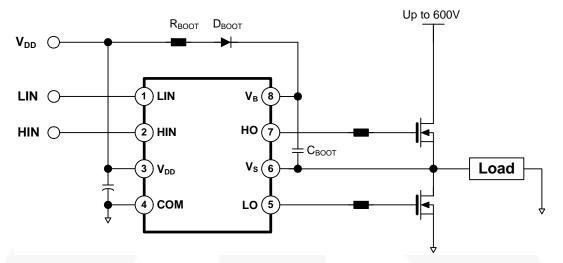


Figure 1. Application Circuit for Half-Bridge

### **Internal Block Diagram**

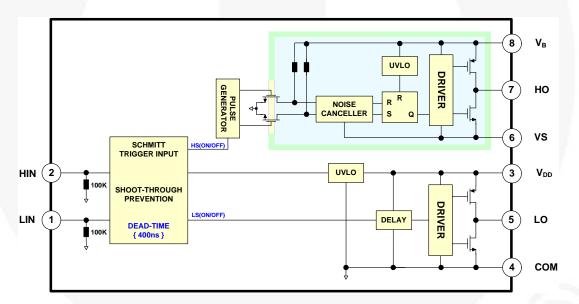


Figure 2. Functional Block Diagram

# **Pin Configuration**

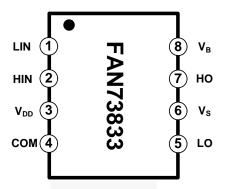


Figure 3. Pin Configuration (Top View)

### **Pin Definitions**

Pin #	Name	Description	
1	LIN	Logic Input for Low-Side Driver	
2	HIN	Logic Input for High-Side Driver	
3	V <sub>DD</sub>	Low-Side Supply Voltage	
4	COM	Logic Ground and Low-Side Driver Return	
5	LO	Low-Side Driver Output	
6	V <sub>S</sub>	High-Side Floating Supply Return	
7	НО	High-Side Driver Output	
8	V <sub>B</sub>	High-Side Floating Supply	

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A=25^{\circ}C$ , unless otherwise specified.

Symbol	Parameter	Min.	Max.	Unit
V <sub>S</sub>	High-side offset voltage	V <sub>B</sub> -25	V <sub>B</sub> +0.3	V
V <sub>B</sub>	High-side floating supply voltage	-0.3	625	V
V <sub>HO</sub>	High-side floating output voltage HO	V <sub>S</sub> -0.3	V <sub>B</sub> +0.3	V
V <sub>DD</sub>	Low-side and logic-fixed supply voltage	-0.3	25	V
V <sub>LO</sub>	Low-side output voltage LO	-0.3	V <sub>DD</sub> +0.3	V
V <sub>IN</sub>	Logic input voltage (HIN/LIN)	-0.3	V <sub>DD</sub> +0.3	V
СОМ	Logic ground and low-side driver return	V <sub>DD</sub> -25	V <sub>DD</sub> +0.3	V
dV <sub>S</sub> /dt	Allowable offset voltage slew rate		50	V/ns
P <sub>D</sub> <sup>(1)(2)(3)</sup>	Power dissipation		0.625	W
$\theta_{JA}$	Thermal resistance, junction-to-ambient		200	°C/W
TJ	Junction temperature		150	°C
T <sub>STG</sub>	Storage temperature	-55	150	°C

#### Notes:

- 1. Mounted on 76.2 x 114.3 x 1.6 mm PCB (FR-4 glass epoxy material).
- 2. Refer to the following standards:
  - JESD51-2: Integral circuits thermal test method environmental conditions natural convection JESD51-3: Low effective thermal conductivity test board for leaded surface mount packages
- 3. Do not exceed P<sub>D</sub> under any circumstances.

### **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit	
V <sub>B</sub>	High-side floating supply voltage	V <sub>S</sub> +11	V <sub>S</sub> +20	V	
V <sub>S</sub>	High-side floating supply offset voltage	6-V <sub>DD</sub>	600	V	
V <sub>DD</sub>	Low-side supply voltage	11	20	V	
V <sub>HO</sub>	High-side (HO) output voltage	V <sub>S</sub>	V <sub>B</sub>	V	
V <sub>LO</sub>	Low-side (LO) output voltage	COM	V <sub>DD</sub>	V	
V <sub>IN</sub> Logic input voltage (HIN/LIN)		COM	V <sub>DD</sub>	V	
T <sub>A</sub>	Ambient temperature	-40	125	°C	

### **Electrical Characteristics**

 $V_{BIAS}$  ( $V_{DD}$ ,  $V_{BS}$ ) = 15.0 V, and  $T_A$ =25°C, unless otherwise specified. The  $V_{IN}$  and  $I_{IN}$  parameters are referenced to COM. The  $V_O$  and  $I_O$  parameters are referenced to  $V_S$  and COM and are applicable to respective outputs HO and LO.

iescent V <sub>BS</sub> supply current iescent V <sub>DD</sub> supply current iescent V <sub>DD</sub> supply current erating V <sub>BS</sub> supply current erating V <sub>DD</sub> supply current set supply leakage current LY SECTION D and V <sub>BS</sub> supply under-voltage sitive going threshold	$V_{IN}$ =0 V or 5 V $V_{IN}$ =0 V or 5 V $f_{IN}$ =20 kHz, rms value $f_{IN}$ =20 kHz, rms value $V_B$ = $V_S$ =600 V	8.2	35 80 420 420	100 200 750 750 10	μΑ μΑ μΑ μΑ
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LY SECTION  D and V <sub>BS</sub> supply under-voltage sitive going threshold	V <sub>B</sub> =V <sub>S</sub> =600 V	8.2		10	μA
D and V <sub>BS</sub> supply under-voltage sitive going threshold		8.2			
sitive going threshold		8.2			
n and Vnc supply under-voltage		0.2	9.2	10.1	V
gative going threshold		7.2	8.3	9.2	V
D supply under-voltage lockout steresis			0.9		V
OUTPUT SECTION					
h-level output voltage, V <sub>BIAS</sub> -V <sub>O</sub>	I <sub>O</sub> =20 mA			1.0	V
w-level output voltage, V <sub>O</sub>				0.6	V
tput high short-circuit pulse current	$V_O=0$ V, $V_{IN}=5$ V with PW<10 $\mu$ s	250	350		mA
tput low short-circuit pulsed current	$V_O$ =15 V, $V_{IN}$ =0 V with PW<10 $\mu$ s	500	650		mA
owable negative V <sub>S</sub> pin voltage for signal propagation to HO			-9.8	-7.0	V
SECTION (INPUT and SHUTDOWN)					
gic "1" input voltage		2.5			V
Logic "0" input voltage				1.2	V
gic "1" input bias current	V <sub>IN</sub> =5 V		50	100	μA
gic "0" input bias current	V <sub>IN</sub> =0 V			2.0	μA
out pull-down resistance		7	100	)	ΚΩ
	o supply under-voltage lockout teresis  OUTPUT SECTION  h-level output voltage, V <sub>BIAS</sub> -V <sub>O</sub> v-level output voltage, V <sub>O</sub> put high short-circuit pulse current put low short-circuit pulsed current owable negative V <sub>S</sub> pin voltage for signal propagation to HO  SECTION (INPUT and SHUTDOWN)  pic "1" input voltage pic "0" input bias current pic "	pative going threshold of supply under-voltage lockout teresis  OUTPUT SECTION  h-level output voltage, V <sub>BIAS</sub> -V <sub>O</sub> uput high short-circuit pulse current uput low short-circuit pulsed current uput low short-circuit pulse	pative going threshold pauply under-voltage lockout teresis  OUTPUT SECTION  h-level output voltage, V <sub>BIAS</sub> -V <sub>O</sub> put high short-circuit pulse current put low short-circuit pulsed current volume to the signal propagation to HO  SECTION (INPUT and SHUTDOWN)  pic "1" input voltage pic "0" input bias current volume to the surrent	pative going threshold O supply under-voltage lockout teresis  OUTPUT SECTION  h-level output voltage, $V_{BIAS}$ - $V_{O}$ put high short-circuit pulse current voltage for signal propagation to HO  SECTION (INPUT and SHUTDOWN)  pic "1" input voltage pic "0" input bias current voltage volt	pative going threshold $7.2$ 8.3 9.2 on $9.2$ o

### Note:

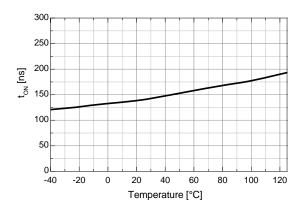
4. This parameter is guaranteed by design.

### **Dynamic Electrical Characteristics**

 $\rm V_{BIAS}\,(V_{DD},\,V_{BS}) = 15.0\,\,V,\,V_{S} = COM,\,C_{L} = 1000\,\,pF,\,and\,\,T_{A} = 25^{\circ}C,\,unless\,\,otherwise\,\,specified.$ 

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
t <sub>ON</sub>	Turn-on propagation delay time	V <sub>S</sub> =0 V		150	270	ns
t <sub>OFF</sub>	Turn-off propagation delay time	V <sub>S</sub> =0 V		140	250	ns
t <sub>R</sub>	Turn-on rising time			50	100	ns
t <sub>F</sub>	Turn-off falling time			30	80	ns
DT	Dead-time		330	450	580	ns

### **Typical Characteristics**



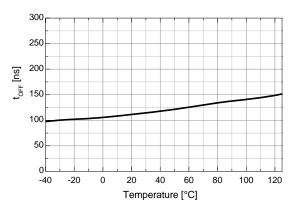
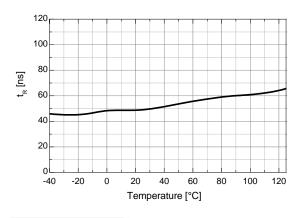


Figure 4. Turn-on Propagation Delay vs. Temp.

Figure 5. Turn-off Propagation Delay vs. Temp.



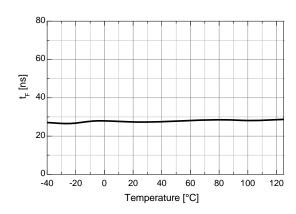
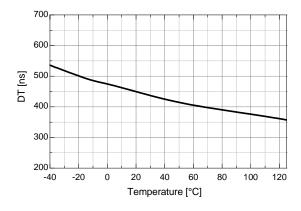


Figure 6. Turn-on Rise Time vs. Temp.

Figure 7. Turn-off Fall Time vs. Temp.



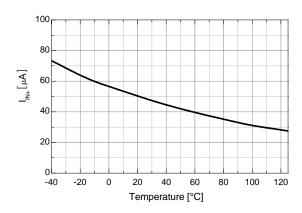
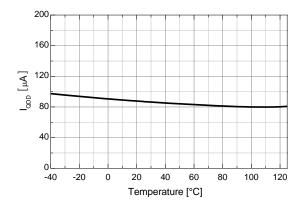


Figure 8. Dead Time vs. Temp.

Figure 9. Logic Input High Bias Current vs. Temp.

### Typical Characteristics (Continued)



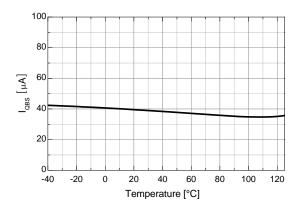
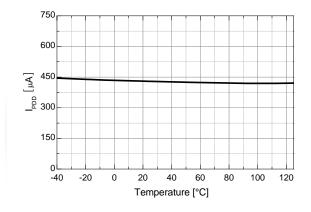


Figure 10. Quiescent  $V_{DD}$  Supply Current vs. Temp.

Figure 11. Quiescent V<sub>BS</sub> Supply Current vs. Temp.



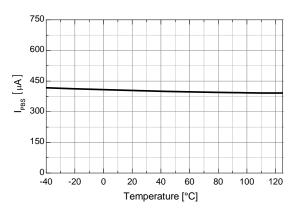
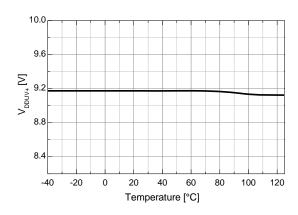


Figure 12. Operating  $V_{\mbox{\scriptsize DD}}$  Supply Current vs. Temp.

Figure 13. Operating  $V_{\mbox{\footnotesize{BS}}}$  Supply Current vs. Temp.



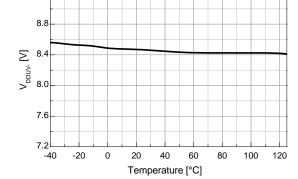
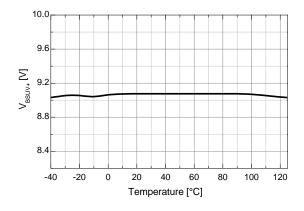


Figure 14.  $V_{\rm DD}$  UVLO+ vs. Temp.

Figure 15.  $V_{\rm DD}$  UVLO- vs. Temp.

### Typical Characteristics (Continued)



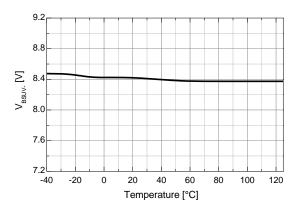
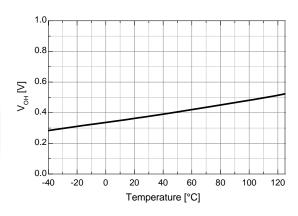


Figure 16. V<sub>BS</sub> UVLO+ vs. Temp.

Figure 17.  $V_{BS}$  UVLO- vs. Temp.



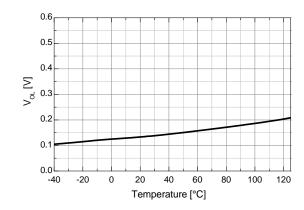
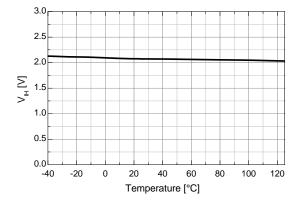


Figure 18. High-Level Output Voltage vs. Temp.

Figure 19. Low-Level Output Voltage vs. Temp.



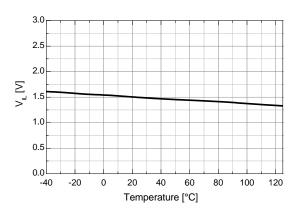


Figure 20. Logic High Input Voltage vs. Temp.

Figure 21. Logic Low Input Voltage vs. Temp.

# Typical Characteristics (Continued)

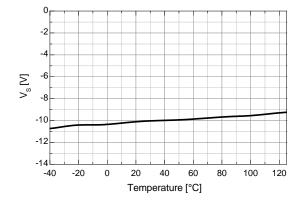


Figure 22. Allowable Negative  $V_S$  Voltage vs. Temp.

### **Application Information**

#### 1. Protection Function

### 1.1 Under-Voltage Lockout (UVLO)

The high- and low-side drivers include under-voltage lockout (UVLO) protection circuitry for each channel that monitors the supply voltage ( $V_{DD}$ ) and bootstrap capacitor voltage ( $V_{BS}$ ) independently. It can be designed prevent malfunction when  $V_{DD}$  and  $V_{BS}$  are lower than the specified threshold voltage. The UVLO hysteresis prevent chattering during power supply transitions.

#### 1.2 Shoot-Through Prevention Function

The FAN73833 has shoot-through prevention circuitry monitoring the high- and low-side control inputs. It can be designed to prevent outputs of high and low side from turning on at same time, as shown Figure 23 and 28.

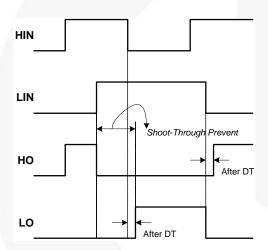


Figure 23. Waveforms for Shoot-Through Prevention

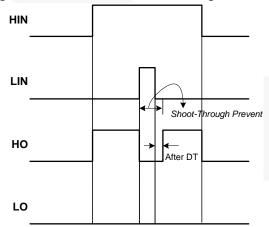


Figure 24. Waveforms for Shoot-Through Prevention

### 2. Switching Time Definitions

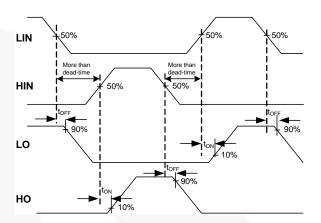


Figure 25. Switching Time Definition

### **Mechanical Dimensions** 1.27 0.65 В 1.75 5.60 6.30 4.15 3.75 5.70 4 **PIN #1 ID** 1.27 ⊕|0.25 M | C | B | A (0.35)LAND PATTERN RECOMMENDATION **TOP VIEW** 1.80 1.75 1.35 1.25 0.51 0.31 (8X) 0.10 OPTION A - BEVEL EDGE 0.10 C **FRONT VIEW** 0.25 0.15 OPTION B - NON BEVEL EDGE NOTES: UNLESS OTHERWISE SPECIFIED BEVEL A. THIS PACKAGE CONFORMS TO JEDEC MS-012 **GAUGE** VARIATION A EXCEPT WHERE NOTED. PLANE R0.10 **B. ALL DIMENSIONS ARE IN MILLIMETERS** 0.25 **SEATING** C OUT OF JEDEC STANDARD VALUE. PLANE D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS. E. LAND PATTERN AS PER IPC SOIC127P600X175-8M 4°-8 F. FILE NAME: MKT-M08B REV1 0.80 0.30 (1.04) DETAIL "B' SCALE 2:1

Figure 26. 8-Lead, Small Outline Package (SOP)

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